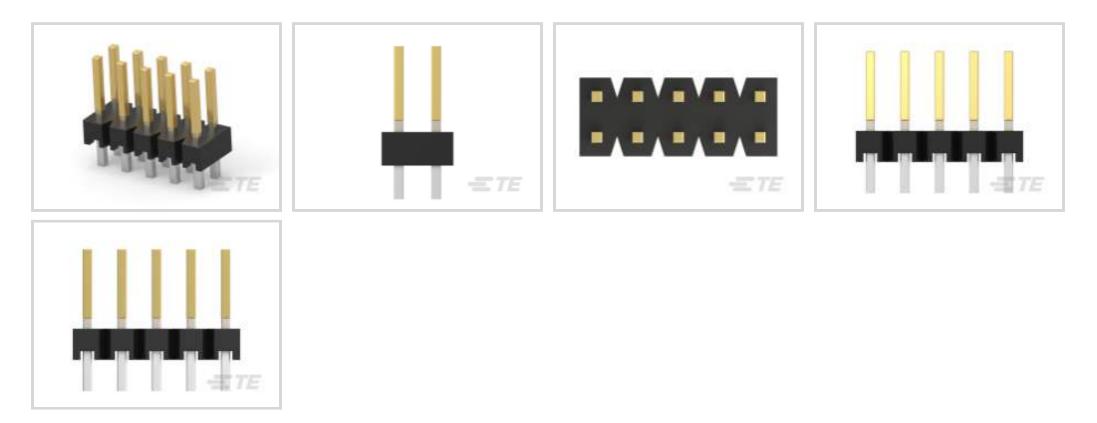
5-146261-5 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-146261-5 PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 10

Number of Rows: 2

Features

E

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Header Type | Breakaway |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 10 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |
| Electrical Characteristics | |
| Operating Voltage | 30 VAC |
| Body Features | |

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers



| Connector Profile | Standard |
|--|----------------------------|
| Primary Product Color | Black |
| Contact Features | |
| Mating Square Post Dimension | .64 mm[.025 in] |
| | 100 – 200 µin |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 2.29 mm[.09 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
| Usage Conditions | |
| Housing Temperature Rating | High |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |

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PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers



Operation/Application

| Solder Process Feature | Board Standoff |
|--|--|
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 320 |
| Packaging Type | Carton |
| Product Compliance For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE |

2023 (235) Does not contain REACH SVHC

Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free

Solder Process Capability

Halogen Content

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

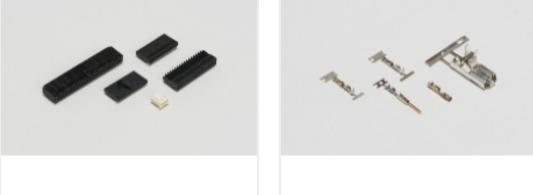
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Also in the Series AMPMODU Headers





| Wire-to-Board Connector Assemblies | Wir | re-to-Board Connector Contacts(65) |
|------------------------------------|-----|------------------------------------|
| & Housings(5) | | |
| | | |

Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers





Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-146261-5_D.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_5-146261-5_D.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-146261-5_D.3d_stp.zip

English

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Product Environmental Compliance

MD_5-146261-5_062820172334_dmtec

English

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English